

Batch Type Microwave Plasma Treatment MW960

High Density Plasma Treatment for Both IC and Wafer

Diverse microwave plasma applications for surface treatment

- Surface cleaning and activation prior to wire bonding or molding
- Plasma cleaning before underfill and solder ball attach

Electrode-free plasma source and high cleaning uniformity

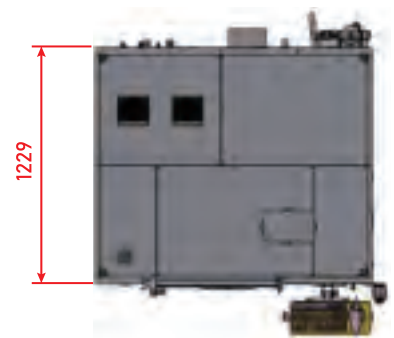
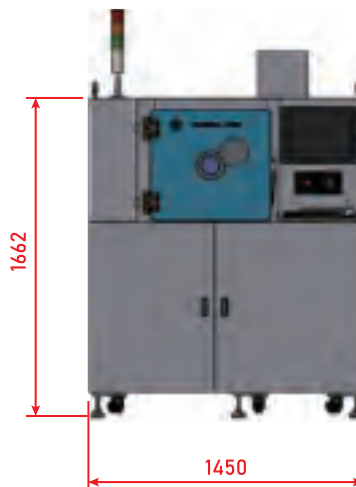
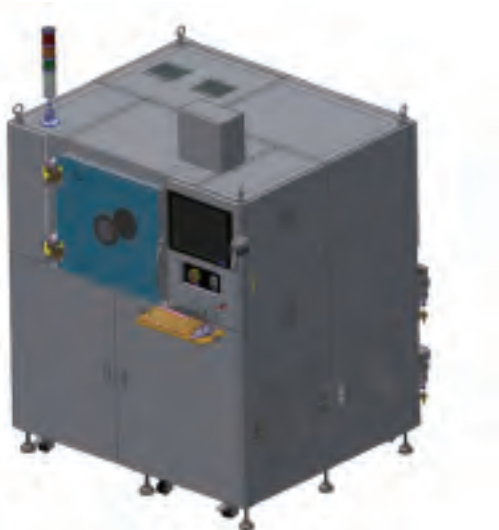
- Microwave plasma to eliminate the risk of ESD
- Side plasma stream and rotary table design to enhance cleaning uniformity

High productivity performance

- High density plasma to enhance processing speed
- Batch type to adapt different carriers for max. 6 magazines



Machine Layout

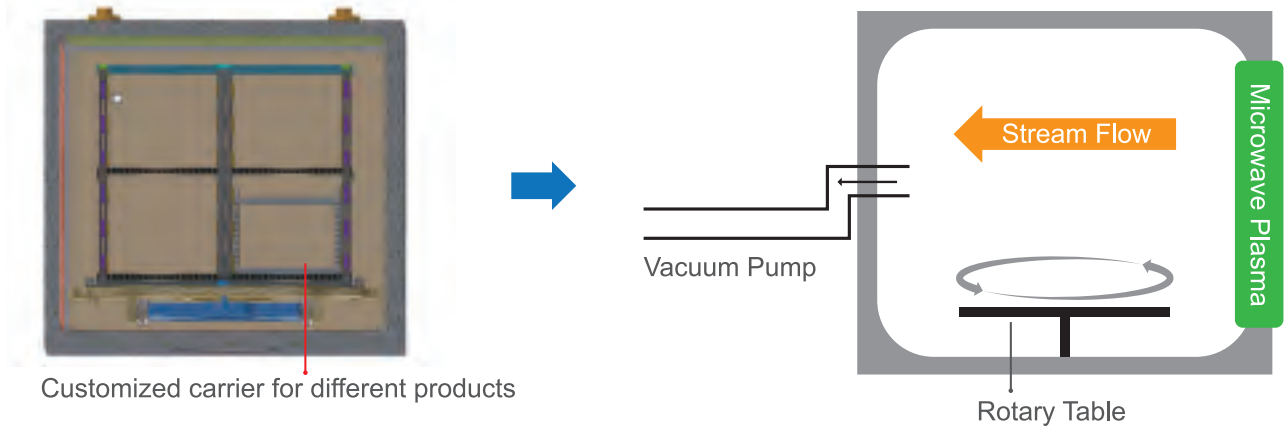


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Chamber Design

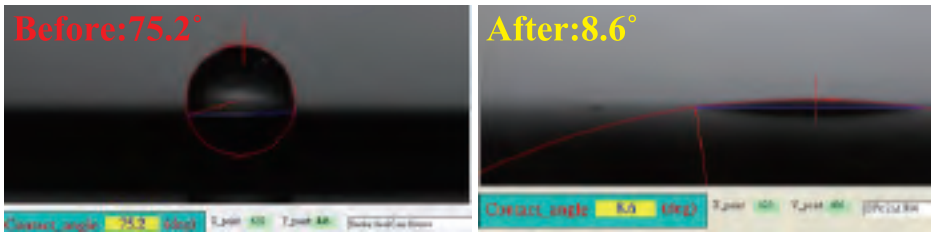
Uniformity improvement solution



Specification

Item	Description
Plasma Source	MW 2KW, 2.45 GHz
Plasma Type	Slot Antenna
Operation Type	Batch Type
Process Pressure	0.05 -0.2 Torr
Base Pressure	<0.03 Torr
Process Temperature	40-70 °C
MFC	Max: 4
Process Gas	Ar /O ₂ /N ₂ /CF ₄
Product Type	Wafer, Leadframe and Substrate
Controller	PC Base
Display	15" LCD Monitor
Chamber	Magazine Type with Rotary Table
WPH	35 pcs/ Plasma @ 10 mins (7 pcs per cassette)

Sample Test



Before:75.2°					Contact angle				
	1	2	3	4	5	6	7	8	9
A	9.3	9.6	9.1	9.9	7.5	8.3	8	9.6	9.7
B	9	6.2	7.7	8.3	5.8	5.8	7.8	9.6	7.4
C	7	4.6	8.6	6.3	7.8	8.2	8.2	9.3	7.7

